

## Supplemental Information

This notice describes the differences between the updated version and its previous version of the IDT82V3155 Data Sheet. It helps readers to identify the changes when the data sheet is upgraded.

## Revision History

Revision Date	PCN Number (if applicable)	Changed Items
November 18, 2004	-	Item 2 - 1

## Changed Items

### November 18, 2004

**Item 2:** Added green package option (page 1, 30)

**Item 1:** Corrected an error description on the State Control Circuit (page 10, 3rd paragraph of the left column)

**Old:** “When changing the operating mode, the TIE control block is enabled/disabled automatically by the state control circuit as shown in [Figure - 3](#), except for the changes from Normal (S1) to Auto-Holdover (S2), and from Auto-Holdover (S2), Holdover (S3) and Short Time Holdover (S4) to Normal (S1). During these four changes, the TIE control block can be enabled or disabled, depending on the logic level on the TIE\_en pin.”

**New:** “When the operating mode is changed from one to another, the TIE control block is automatically disabled as shown in [Figure - 3](#), except the changes from Holdover (S3) or Auto-Holdover (S2) to Normal (S1). In the case of changing from S3 or S2 to S1, the TIE control block is enabled or disabled by the TIE\_en pin.”

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